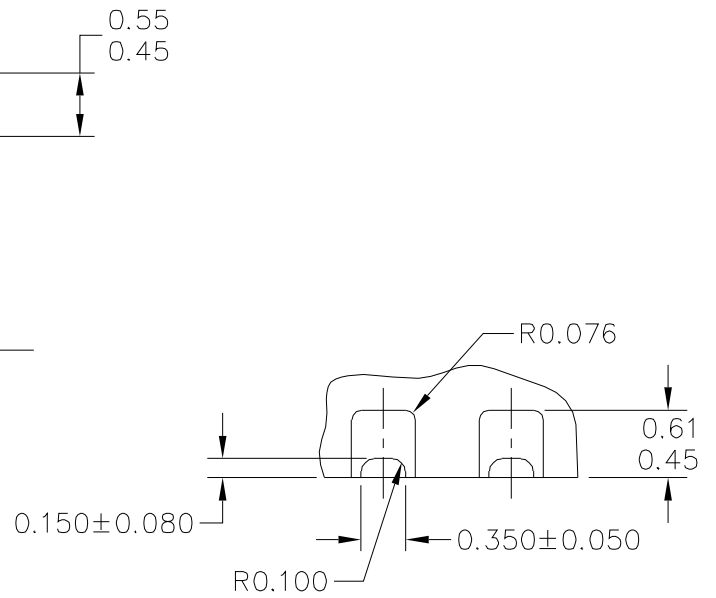
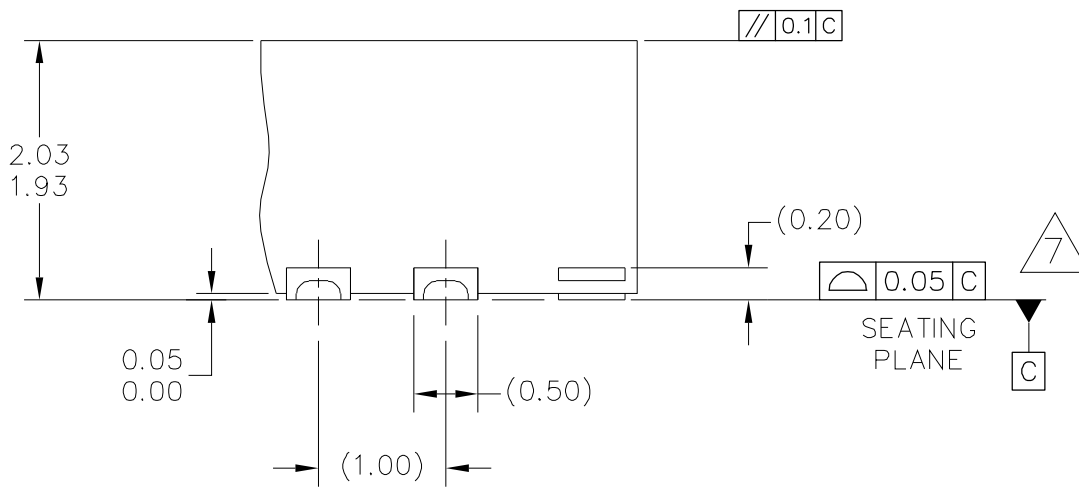


DETAIL M



DETAIL A



DETAIL G
VIEW ROTATED 90°CW

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN), 16 TERMINAL, 1.0 PITCH (6 X 6 X 1.98)	DOCUMENT NO: 98ASA00090D	REV: C	
	CASE NUMBER: 2086-01	26 MAY 2011	
	STANDARD: NON-JEDEC		

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. – 1994.

4. THIS DIMENSION APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TIP. IF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION b SHOULD NOT BE MEASURED IN THAT RADIUS AREA.

5. MAX. PACKAGE WARPAGE IS 0.05 MM.

6. PIN #1 ID ON TOP WILL BE LASER MARKED.

7. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.

8. THIS IS NON JEDEC REGISTERED PACKAGE.

10. MIN. METAL GAP SHOULD BE 0.2 MM

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